

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-3. (Canceled)

4. (Previously presented) A semiconductor device having an element forming region where a semiconductor element is formed and an element non-forming region where a semiconductor element is not formed, on a front surface of a silicon substrate, comprising:

a plurality of grooves formed in a rear surface of said substrate corresponding to said element non-forming region; and

wherein said grooves are formed to extend in directions crossing each other.

5. (Original) The semiconductor device of claim 4, wherein said grooves are formed to extend in directions which cross substantially perpendicular to each other.

6. (Original) The semiconductor device of claim 4, wherein said grooves are formed to extend in three different directions.

7-12. (Canceled)

13. (Previously presented) A semiconductor device module comprising
a semiconductor device bonded to a bonding substrate, wherein said semiconductor device has an element forming region where a semiconductor element is formed and an element

non-forming region where a semiconductor element is not formed, on a front surface of a silicon substrate, and a groove formed in a portion of a rear surface of said silicon substrate corresponding to said element non-forming region; and
wherein said bonding substrate is curved.

14-30. (Canceled)